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By:

LINDA E. HASTINGS

Any fee due as a result of this paper, not covered by an enclosed check, may be charged on Deposit Acct. No. 50-1290.

Attorney Docket No.: NECF 18.363A (100806-00248)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor : Hirokazu HONDA
Conformation No. : 4217
Serial No. : 10/761,510
Filed : January 21, 2004
Title : FLIP-CHIP TYPE SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE SAME
Examiner :
Group Art Unit : 2841

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

SIR:

Prior to an Office Action on the merits, please amend the above-captioned
application as follows: